江苏	图	图号: 314BD002 版本 A.C					A. 0			
		传输进料方向 个孔为椭圆孔 ————————————————————————————————————								
					序殊要求(Remark&Special Instruction)					
1,63										
VDD16 9 00										
		5 5000						_		
GND1 8										
単顶针 多顶针	点胶 画胶									
• /	• /						, 	<u>→</u> \		
产品型号 (Product Type):	HS9000P-P16	线材直径 (Wire Diameter):	银合金线0.		芯片减 (Chip th thicknes		220±10um			
芯片名称 (Die Name):	HS5122	压焊点尺寸 (Pad Opening):	50. 35×50.	. 35um	装片胶	首选	9246L	.B5(导	电胶)	
芯片尺寸: (Die Size):	0.5548×0.4332mm	最小压焊间距 (Min Pitch):	59.85um		(Epoxy)	备选	S6100	交)		
封装形式 (Package Type):	SOP16L(9.9×3.9×1.4 e=1.27)	先焊线 (Wire Bond Start):	PIN1		塑封料 首选 (Molding		GR710GN			
引线框 (Lead Frame):	SOP16L(12R)(94×150)	焊线总数 (Quantity of Wire):	18		Compound)	备选	/			
L/F电镀方式 (L/F Plating Type):	雾 锡	最长线长(Length of longest Wire):	2.34mm		CUP/BOAC		YES		NO	
晶圆尺寸 (Wafer Size):	/	项层铝厚 (Top Al Thickness):	1um(3层)		RF 芯片		YES		NO O	
吸嘴 (suction nozzle)	RR10×10	切割道(Cutting Way)	60um		LOW-K芯片		YES		NO	
拟制 Prepared by	钱培丽 2022.6.8	审核 Checked by			批准 Approved by					